

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (currently amended): A circuit board made of resin with pins, comprising:

flat pins each including:

a rod portion having a diameter of not greater than 0.35 mm, and

a concentric tabular large diameter portion having a larger diameter than that of the rod portion formed on one end of the rod portion,

the flat pins each being soldered to a pin bonding portion provided on ~~the~~ a main surface of ~~a the~~ board at the large diameter portion, wherein

the ratio (W/S) of the diameter of the large diameter portion to the rod portion is from not smaller than 2.16 to not greater than 2.67, if the diameter of the rod portion and the large diameter portion of the flat pin are S and W, respectively,

wherein

the formed thickness of a solder layer is adjusted to be not greater than 0.30 mm along the vertical direction from the first main surface of the pin bonding portion toward the flat pin.

2. (currently amended): ~~The~~ A circuit board made of resin with pins ~~as defined in Claim 1,~~ comprising:

flat pins each including:

a rod portion having a diameter of not greater than 0.35 mm, and

a concentric tabular large diameter portion having a larger diameter than that of the rod portion formed on one end of the rod portion,

the flat pins each being soldered to a pin bonding portion provided on a main surface of the board at the large diameter portion, wherein

the ratio (W/S) of the diameter of the large diameter portion to the rod portion is from not smaller than 2.16 to not greater than 2.67, if the diameter of the rod portion and the large diameter portion of the flat pin are S and W, respectively,

wherein

the ratio (T/S) of the thickness of the large diameter portion to the diameter of the rod portion is from not smaller than 0.40 to not greater than 0.67, if the thickness of the large diameter portion is T.

3. (original): The circuit board made of resin with pins as defined in Claim 2, wherein the ratio (W/S) of the diameter of the large diameter portion to the rod portion is from not smaller than 2.33 to not greater than 2.67, and

the ratio (T/S) of the thickness of the large diameter portion to the diameter of the rod portion is from not smaller than 0.40 to not greater than 0.54.

4. (canceled).

5. (original): The circuit board made of resin with pins as defined in Claim 1, wherein

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the flat pins are each made of a metal material containing at least copper.

6. (currently amended): The circuit board made of resin with pins as defined in Claim 1,
wherein

a top portion of the concentric tabular large diameter portion is exposed from ~~the~~ a solder
layer.